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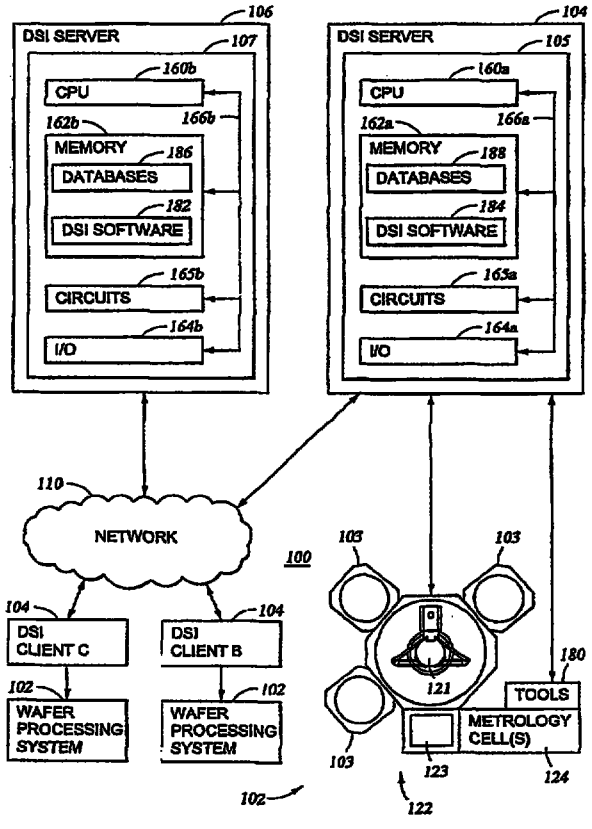
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(54) Title: DEFECT SOURCE IDENTIFIER



(57) Abstract: A method and associated apparatus of analyzing defects on semiconductor wafers. The method includes identifying defects on the semiconductor wafer. Defect inspection information is created within a defect source identifier client. The defect inspection information containing information regarding the identified defects. The defect inspection information is transmitted through a network to a defect source identifier server. Defect source information is derived at the defect source identifier server in response to the defect inspection information. The defect source information is transmitted from the defect source identifier server to the defect source identifier client. The defect source information is utilized at the defect source identifier client. In one aspect, the utilizing the defect solution information involves displaying defect solutions to the defect at the defect source identifier client in response to the defect solution information. In another aspect, utilizing the defect solution information involves altering the operation of the wafer processing system.

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